



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akira SATO

Group Art Unit: 2825

Application No.: 09/424,500

Examiner: G. Lee, Jr.

Filed: February 22, 2000

Docket No.: 104788

For: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, MOLDING  
DEVICE FOR SEMICONDUCTOR DEVICE, AND SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the March 13, 2002, Office Action, the period for reply being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

IN THE DRAWINGS:

Please correct Figure 2 pursuant to the attached Request for Approval of Drawing Corrections.

IN THE SPECIFICATION:

Page 15, lines 12 through page 16, line 1, delete current paragraph and insert therefor:

Fig 8 shows a fifth embodiment of the present invention. In this embodiment, a semiconductor device having a heat sink is manufactured. A heat radiator 70 is disposed in the cavity 38 of the lower mold 36 and supported by the support pin 42 as shown by the broken line in Fig. 8. A recess 72 is formed in the center of the bottom of the heat radiator 70 for preventing mispositioning. The upper end of the support pin 42 is secured in the recess

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